



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

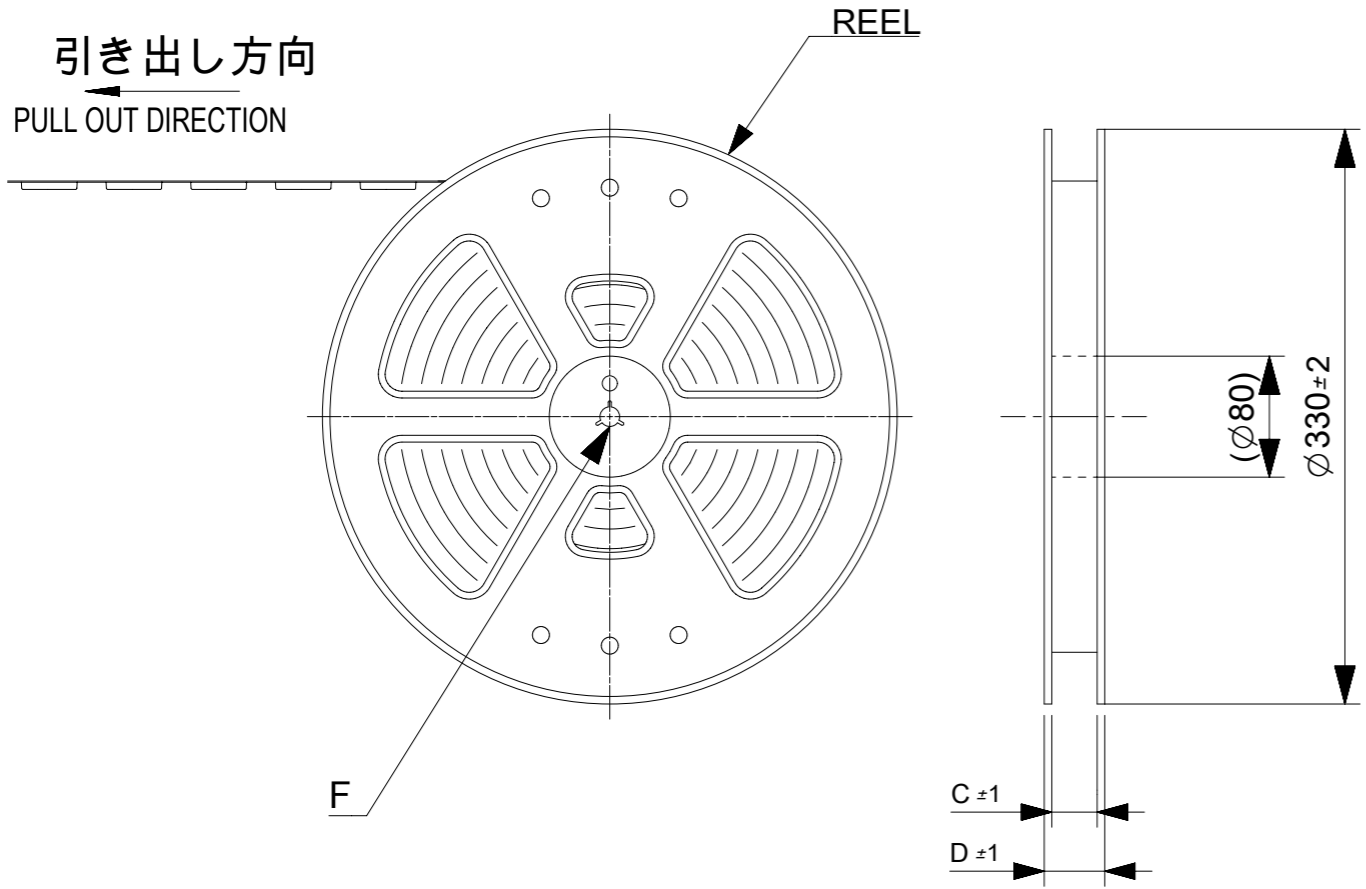
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



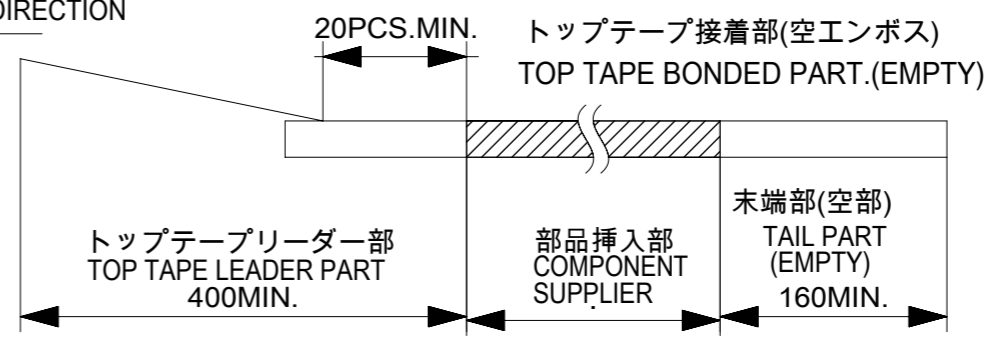
引き出し方向
PULL OUT DIRECTION



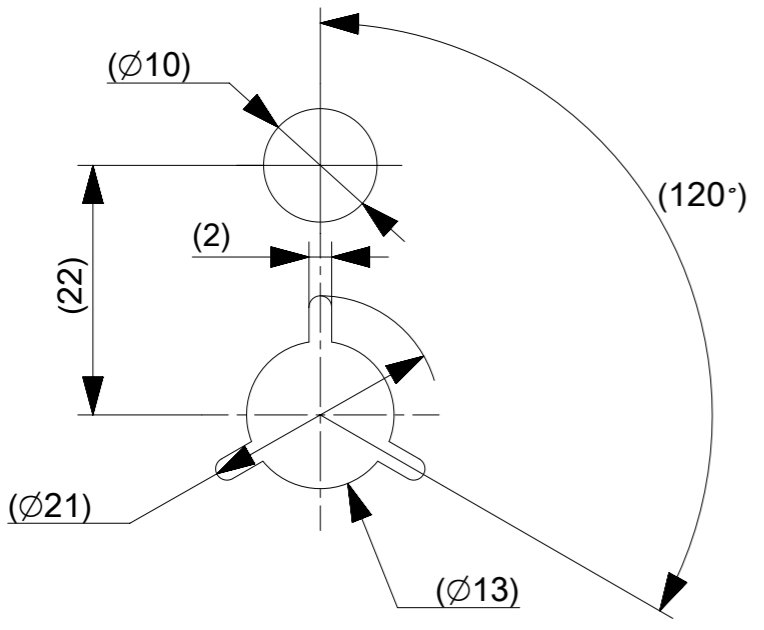
NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, SEE PRODUCT DRAWING.
- 梱包数量 : 3000個 / リール
NUMBER OF CONNECTORS : 3000 PCS/REEL.
- リードテープ長さ LEAD TAPE LENGTH.

引き出し方向
PULL OUT DIRECTION



- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
- 材料 MATERIAL
キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL) ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

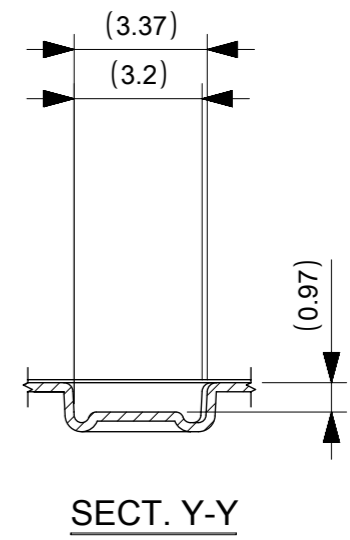
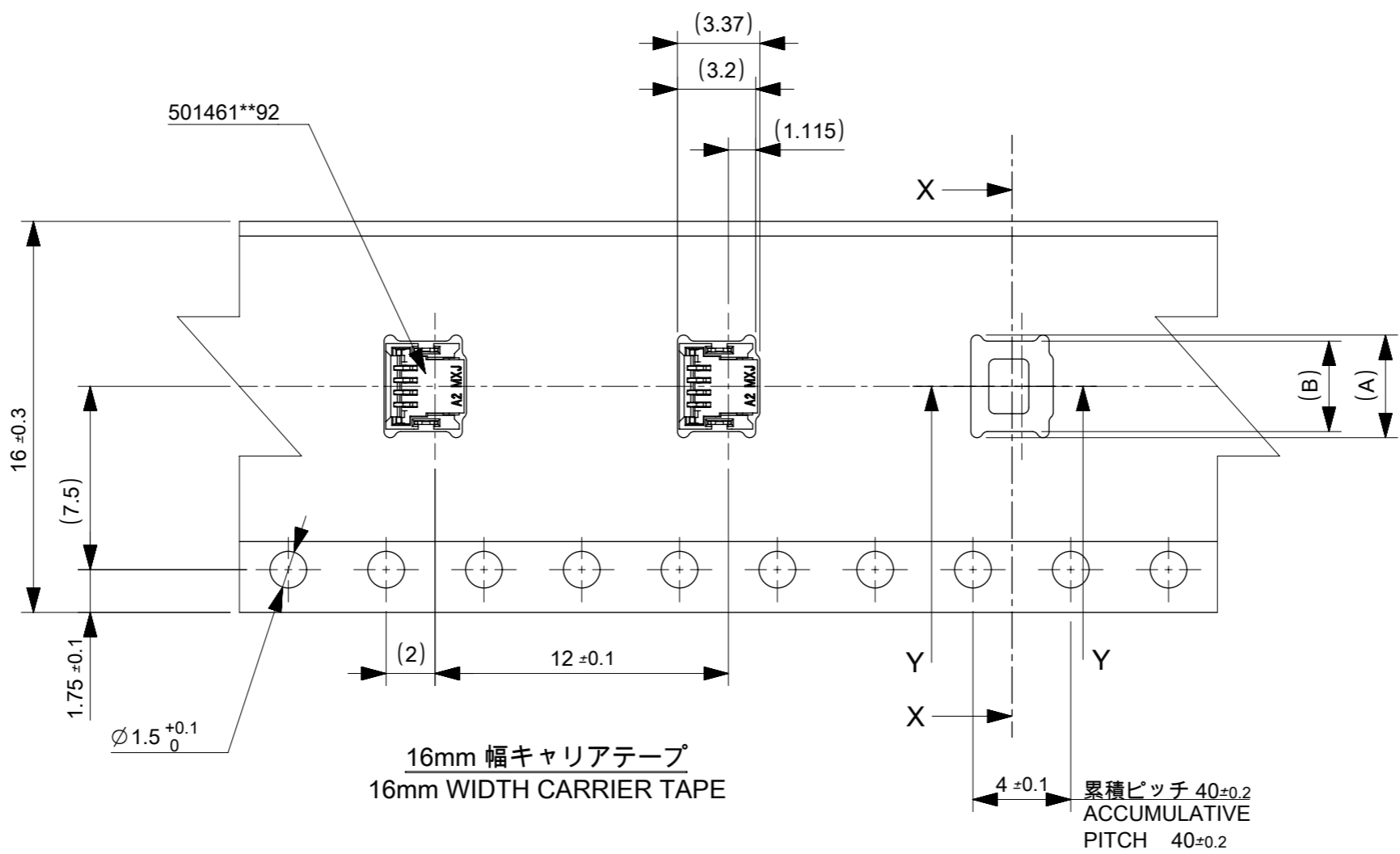
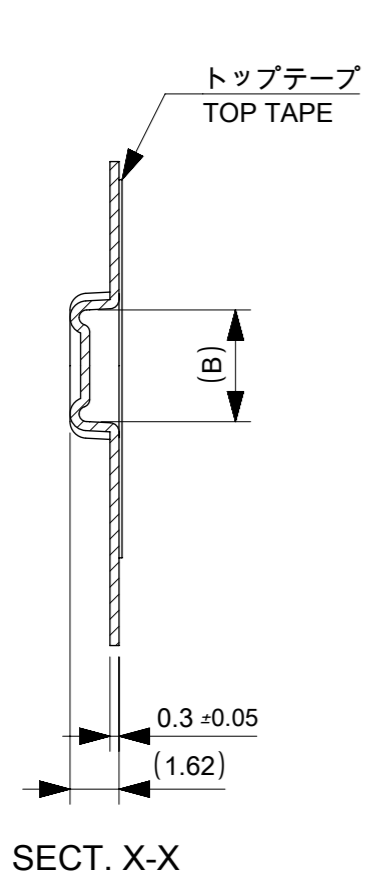


DETAIL F

501461**91 MODEL NO.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
REDRAW	EC NO: 102256	DRWN: NVELUSAMY	CHK'D: HIJIMA	APPR: YNOGAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE				
	2015/12/09	2015/12/24	2015/12/24	2015/12/24	ANGULAR TOL ± °	MM	---				
	4 PLACES	±	DRWN BY	DATE	0 PLACES	±	NVELUSAMY	2015/12/09	0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG LOW-HALOGEN		
	3 PLACES	±	CHK'D BY	DATE	1 PLACE	±	HIJIMA	2015/12/24			
	2 PLACES	±	APPR BY	DATE	0 PLACES	±	YNOGAWA	2015/12/24			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					DRAWING SIZE	THIRD ANGLE PROJECTION	PRODUCT CUSTOMER DRAWING				
					A3		SERIES	MATERIAL NUMBER	CUSTOMER		
							501461	SEE CHART	GENERAL		
							DOCUMENT NUMBER		DOC TYPE	DOC PART	SHEET NUMBER
							5014610001		PSD	000	1 OF 2

引き出し方向
PULL OUT DIRECTION



16	21.4	17.4	5.7	6.2	5014610891	8
			4.7	5.2	5014610691	6
			4.2	4.7	5014610591	5
			3.7	4.2	5014610491	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	EMBOSSED PACKAGE ORDER NO. オーダー番号	極数 CIRCUITS
CONNECTOR SERIES NO:501461**92						

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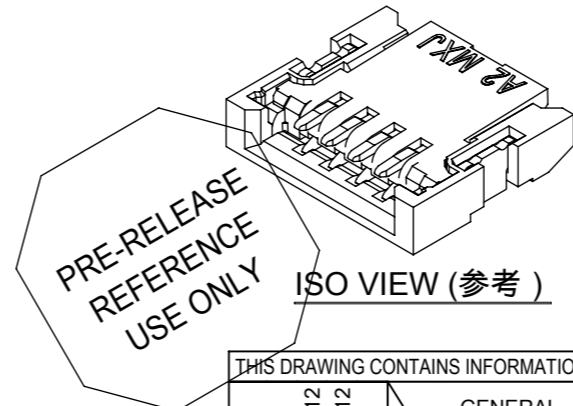
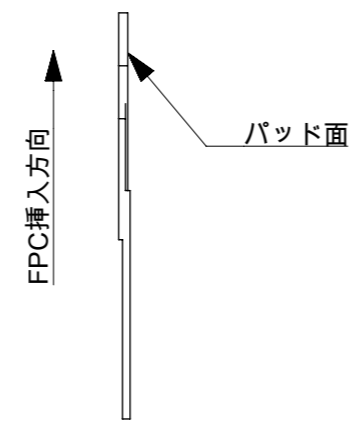
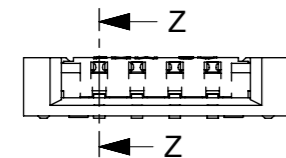
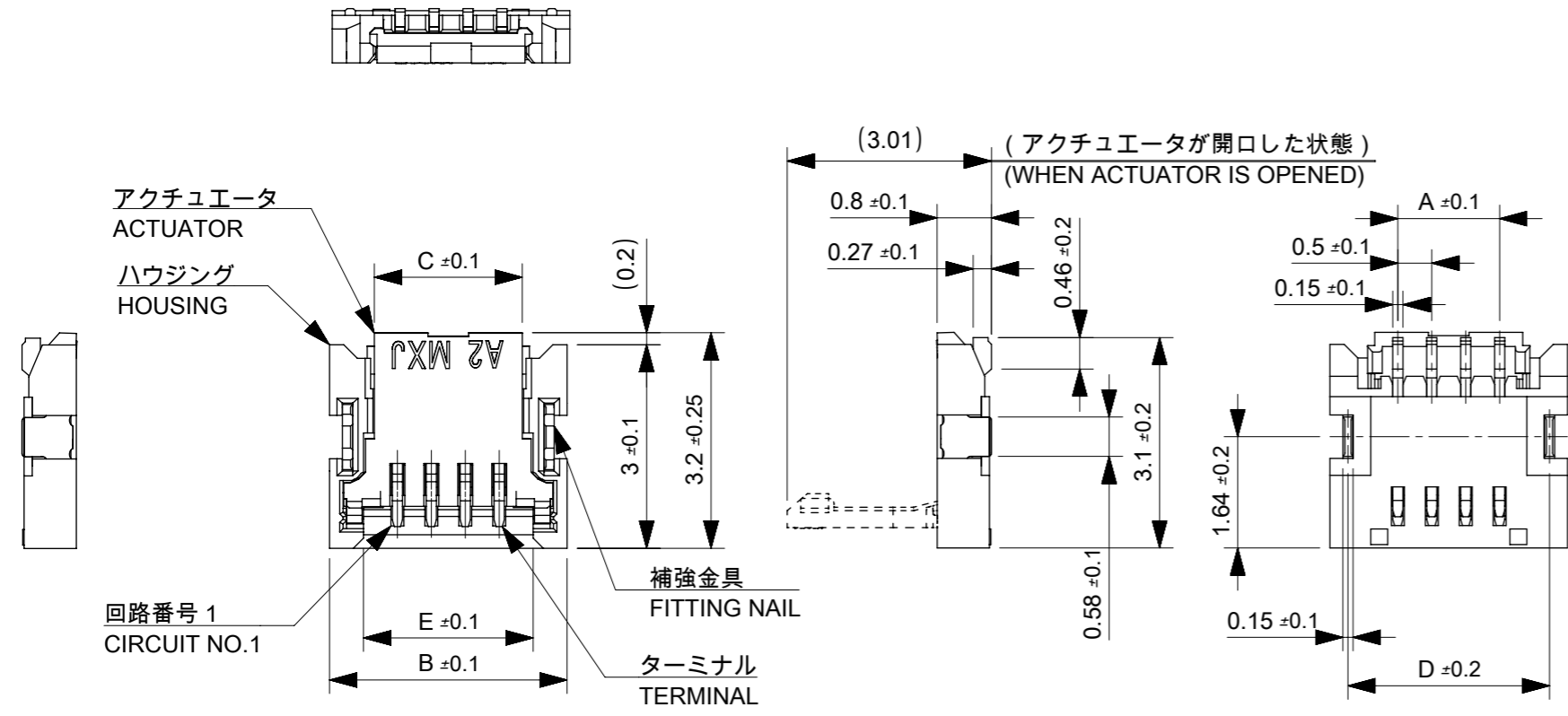
REDRAW EC NO: 102256 DRWN: NVELUSAMY CHK'D: HIJIMA APPR: YNOGAWA 2015/12/09 2015/12/24 2015/12/24	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE			
	ANGULAR TOL ±	MM	---			
	4 PLACES ±	DRWN BY	DATE		0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG LOW-HALOGEN	
	3 PLACES ±	NVELUSAMY	2015/12/09			
	2 PLACES ±	CHK'D BY	DATE			
	1 PLACE ±	HIJIMA	2015/12/24		PRODUCT CUSTOMER DRAWING	
0 PLACES ±	APPR BY	DATE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	YNOGAWA	2015/12/24	DRAWING SIZE	THIRD ANGLE PROJECTION		
A	A3		501461	SEE CHART	GENERAL	
REV			DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
			5014610001	PSD	000	2 OF 2

E

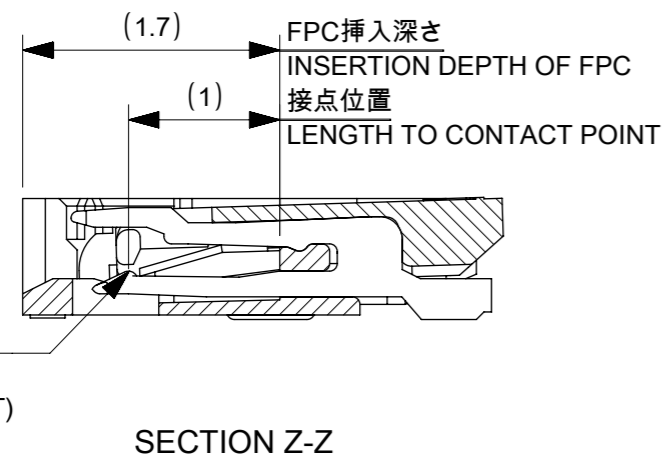
注記

NOTES:

- 材質
 MATERIAL
 ハウジング：黒色、ポリアミド(PA46)、ガラス充填、UL94HB
 HOUSING:BLACK,POLYAMIDE,GLASS FILLED,UL94HB
 アクチュエーター：ナチュラル(白色)、ポリアミド(PA46)、ガラス充填、UL94HB
 ACTUATOR:NATURAL(WHITE),POLYAMIDE,GLASS FILLED,UL94HB
 ターミナル：リン青銅 (t = 0.15)
 TERMINAL:PHOSPHOR BRONZE (t=0.15)
 補強金具：リン青銅 (t = 0.15)
 NAIL:PHOSPHOR BRONZE (t=0.15)
- めっき仕様
 PLATING
 ターミナル：接点部：部分金メッキ(0.1μm以上)
 テール部：部分金メッキ
 下地 ニッケルメッキ(1.0μm以上)
 TERMINAL : CONTACT AREA :SEPARATED GOLD PLATING
 (0.1 MICROMETER MINIMUM)
 SOLDER TAIL AREA :SEPARATED GOLD PLATING
 UNDER PLATING ; NICKEL PLATING OVERALL
 (1.0 MICROMETER MINIMUM)
 補強金具：錫メッキ(1.0μm以上)
 下地 ニッケルメッキ(1.0μm以上)
 FITTING NAIL : TIN PLATING 1.0 MICROMETER MINIMUM.
 UNDER PLATING ; NICKEL PLATING OVERALL
 (1.0 MICROMETER MINIMUM)
- 平坦度は、0.1mm以下とする。
 TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.
- ELV&RoHS COMPLIANT

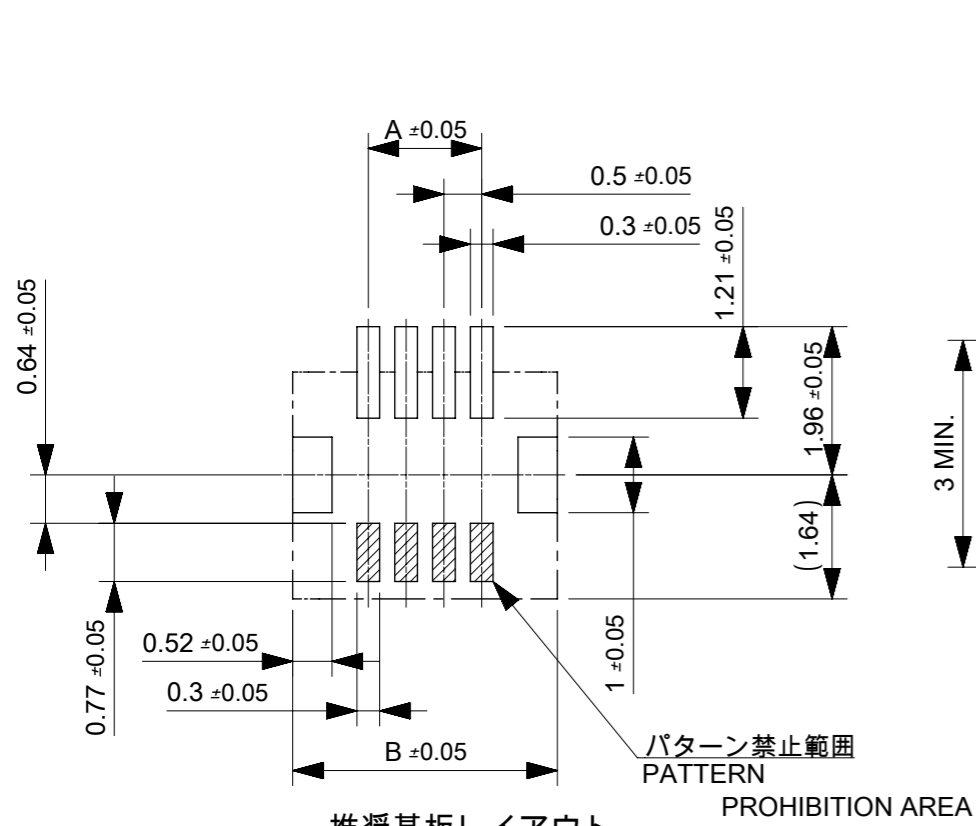


4.5	4.97	4.18	5.5	3.5	5014610891	8
3.5	3.97	3.18	4.5	2.5	5014610691	6
3.0	3.47	2.68	4.0	2.0	5014610591	5
2.5	2.97	2.18	3.5	1.5	5014610491	4
E	D	C	B	A	EMBOSSED TAPE PKG.	極数(N)
ORDER NO. オーダー番号						CIRCUITS(N)
CONNECTOR NO.						5014610492

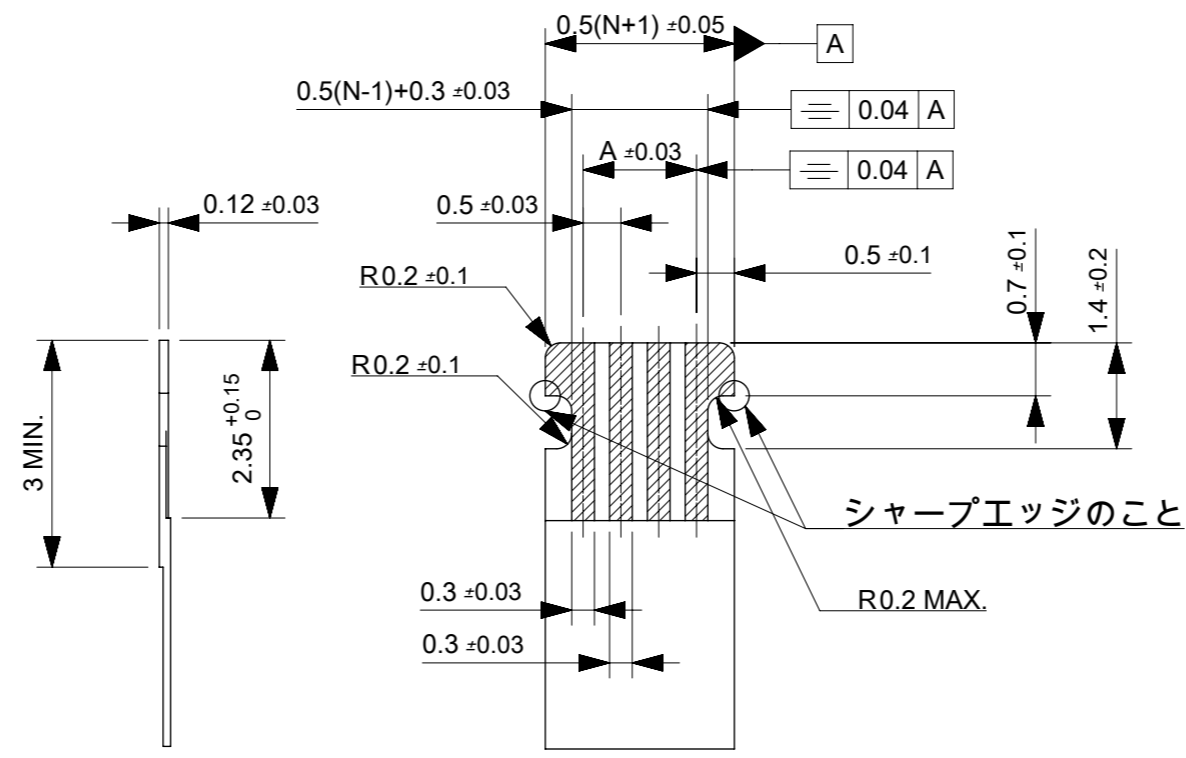


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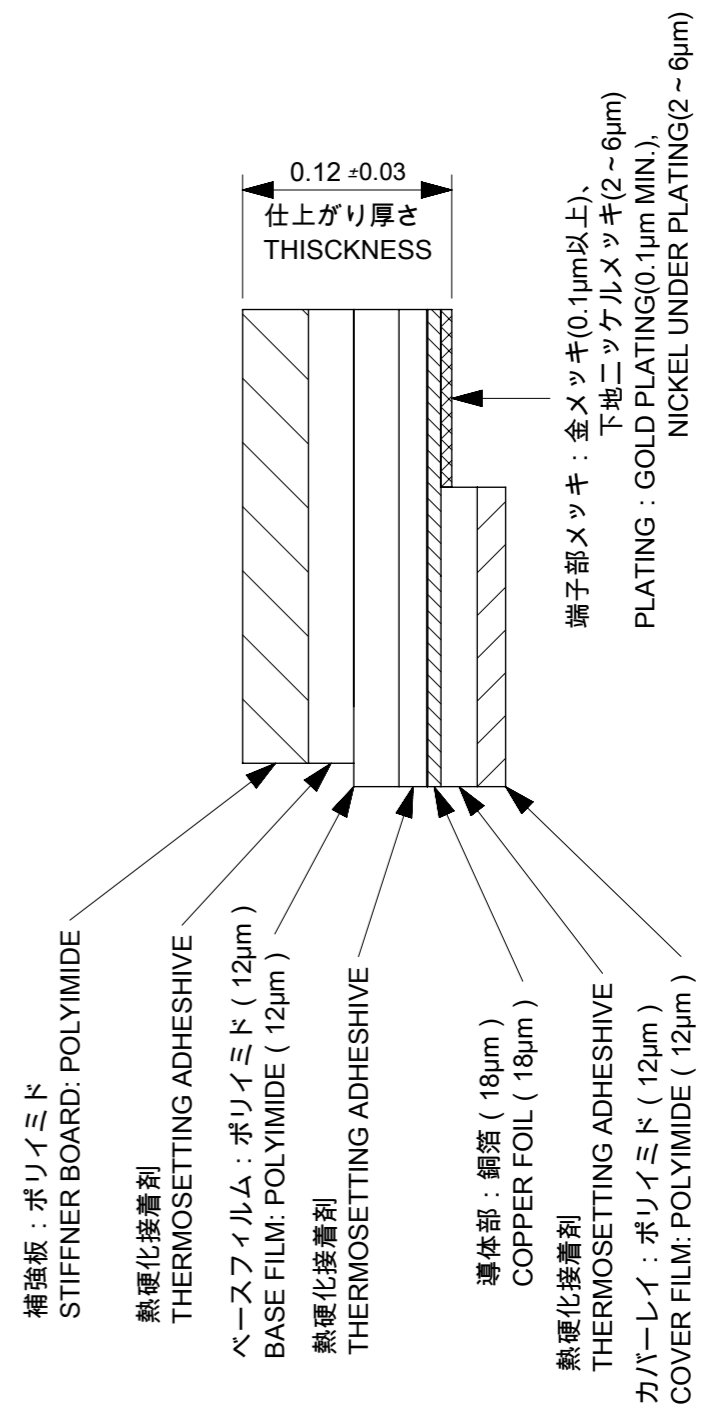
REVISED	2016/01/12	2016/01/12	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE		
	DRWN: MTAKAHASHI04	CHK'D: KTAKAHASHI		MM	10:1		
	4 PLACES ±	ANGULAR TOL ± °		DRWN BY	DATE		NVELUSAMY 2015/12/09
	3 PLACES ±	2 PLACES ±		CHK'D BY	DATE		HIIJIMA 2015/12/24
1 PLACE ±	0 PLACES ±	APPR BY	DATE	YNOGAWA 2015/12/24	PRODUCT CUSTOMER DRAWING SERIES: 501461 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING SIZE	THIRD ANGLE PROJECTION	A3			
RELEASE STATUS		RQ	RELEASE DATE	18.01.2016 05:13:29		DOCUMENT NUMBER: 5014611004 DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 1 OF 2	



推奨基板レイアウト
RECOMMENDED P.C. BOARD PATTERN LAYOUT
 マスク厚 : 120μm
 マスク開口率 : 100%
 SCREEN THICKNESS : 120μm
 SCREEN OPEN RATIO : 100%



適合金メッキFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING RECOMMENDED DIMENSION
 仕上がり厚さ : 0.12±0.03
 THICKNESS : 0.12+0.03/-0.03



補強板 : ポリイミド
 STIFFNER BOARD: POLYIMIDE
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 ベースフィルム : ポリイミド (12μm)
 BASE FILM: POLYIMIDE (12μm)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 導体部 : 銅箔 (18μm)
 COPPER FOIL (18μm)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 カバーレイ : ポリイミド (12μm)
 COVER FILM: POLYIMIDE (12μm)
 端子部メッキ : 金メッキ (0.1μm以上)、
 下地ニッケルメッキ (2~6μm)
 PLATING : GOLD PLATING (0.1μm MIN.),
 NICKEL UNDER PLATING (2~6μm)

FPCについて :

抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

ABOUT FPC :

RECOMMENDED PUNCHER DIRECTION :
 FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
 RECOMMENDED MATERIAL :
 STIFFNER FILME : POLYIMIDE
 BONDING AGENT : THRMOSSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

PRE-RELEASE
 REFERENCE
 USE ONLY

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REVISED	2016/01/12	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	molex			
	2016/01/12		MM	10:1				
	EC NO: 102468		DRWN: MTAKAHASHI04	DRWN BY		DATE	0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY LOW-HALOGEN	
	CHK'D: KTAKAHASHI		CHK'D BY	DATE		PRODUCT CUSTOMER DRAWING		
APPR:		4 PLACES ±	NVELUSAMY	2015/12/09	SERIES	MATERIAL NUMBER	CUSTOMER	
		3 PLACES ±	HIIJIMA	2015/12/24	501461	SEE CHART	GENERAL	
		2 PLACES ±	YNOGAWA	2015/12/24	DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
		1 PLACE ±			5014611004	PSD	000	2 OF 2
		0 PLACES ±						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION				
			A3					